In the Specification:

Please make the following changes at the indicated locations in the indicated specification paragraphs:

Page 4, lines 6 to 9:

Relative motion of the parts occurs without tearing off the contact element. The contact junction is reproducible and not dependent on the bond forming and processing ~~bonding form and process~~. Thus the electrical tuning between the wave guide and the conductor strip is reproducible.

Page 4, lines 10 to 16:

The coil spring for applications in high-frequency ~~the highest frequency~~ engineering is especially small (length, about 100 to 200 μm, thickness about 50 μm). The coil spring is formed with very great accuracy, particularly as a so-called MIGA coil spring ~~(MIGA = microgalvanic)~~ (MIGA means microgalvanic). UV depth lithography or comparable methods of structuring polymers in combination with multilayer microgalvanic methods are suitable for making the coil spring. Laser processing or high precision punching or stamping can be suitable for making the coil spring.

Page 6, lines 4 to 11:

According to figures 1 to 5, a ~~A~~ wave guide 1, which is in the form of a stepping transformer, and a conductor strip substrate 2 rest on a metal plate 5. The wave guide is screwed on the metal plate 5. The form of the stepping transformer is not described here in detail. The conductor strip substrate 2 is glued on the metal plate 5 with the help of an electrically conductive adhesive material or glue 6. ~~The conductor strip substrate 2 is provided on its upper side with a conductor strip 7.~~ A conductor strip 7 is provided on the upper side of the conductor strip substrate 2. This conductor strip is a component of a microwave IC (MIC). The wave guide 1 has a coupling opening 8 (see figure 1) in the vicinity of the conductor strip. However the conductor strip 7 and conductor strip substrate 2 are located outside of the wave guide 1 as shown in figures 1 to 5.

Page 6, line 12, to page 7, line 2:

According to figure 1, a coil spring 11 operating as an electrically conductive contact element is bonded to the conductor strip 7 at a first contacting area 9 with an electrically conducting glue or adhesive. Silver-filled epoxy resin glue is suitable as the adhesive material. The wave guide 1 is assembled after the coil spring 11 has been bonded with the adhesive, so that the mechanically pre-tensioned coil spring 11, which forms a sliding contact 10 at a second contacting area 9', presses resiliently against an exterior ~~a~~ surface 1a of the wave guide 1, which extends substantially perpendicularly to the plane of the

conductor strip 7. The contact element forms a low impedance contact between the wave guide 1 and the conductor strip 7. The low impedance connection is required in order to permit an optimum tuning of the coupling of the electromagnetic waves from the wave guide 1 into the conductor strip 7. Besides the geometry of the junction plays an important role ~~roll~~.

Page 7, lines 3 to 7:

Relative motions, especially thermally dependent relative motions, between the wave guide 1 and the conductor strip 7 are compensated with the help of the sliding contact 10 and the spring force of the coil spring 11. Without this device, the contacting areas would be subjected to impermissibly large mechanical stresses.

Page 7, lines 8 to 11:

Figure 2 illustrates another embodiment for the coil spring 12. This embodiment is similar to the embodiment shown in Fig. 1, but differs from it because the surface 1b of the wave guide 1 on which the coil spring 12 bears is substantially parallel to the conductor strip 7 and inside the coupling opening 8 of the wave guide. In this embodiment also the coil spring 12 acting as contact element is fixed to the conductor strip 7 at a first contacting area 9 by an electrically conductive adhesive. Similarly the coil spring 12 bearing on the surface 1b of the wave guide 1 at the other contacting area 9' forms a sliding contact 10 in electrical contact with the wave guide 1.

Page 7, lines 12 to 16:

This latter situation in regard to Fig. 2 is also true of the third embodiment shown in Fig. 3. In the embodiment shown in Fig. 3, the coil spring 13 is bonded to the conductor strip 7 at a first contacting area 9 with an electrically conductive glue or adhesive. The ~~a~~ sliding contact 10 of the ~~a~~ coil spring 13 with the wave guide 1 is located at another contacting area 9' in a cavity 1c of the wave guide 1. It is also possible to additionally secure the spring contact in the cavity with a highly flexible electrically conductive glue or adhesive material.

Page 7, lines 17 to 19:

In the embodiment shown in Fig. 4, a coil spring 14 is electrically conductively glued to the wave guide 1 at one contacting area 9, while the sliding contact 10 makes electrical contact on the conductor strip 7 on the other conducting area 9'.

Page 7, line 20, to page 8, line 2:

In Figure 5, in a fifth embodiment, the coil spring 15 has a curved U-shape. A first contacting area 9 of the ~~The~~ coil spring 15 is glued in an electrically conductive manner to ~~a first contacting area 9 on~~ the conductor strip 7. The other contacting area 9' of the coil spring 15 is formed as an electrically conducting adhesive area 16. This adhesive area 16 can however be ~~by~~ highly flexible. The coil spring 15 need not then be formed so that it is U-shaped.